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Docket No. 221608US0PCT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Minoru TAKAYA, et al.

SERIAL NO: 10/089,067

GAU:

FILED: April 5, 2002

EXAMINER:

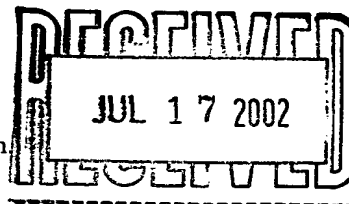
FOR: SOLDERING FLUX, SOLDER PASTE AND METHOD OF SOLDERING

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Applicant(s) wish to disclose the following information



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REFERENCES

- ☒ The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- ☐ Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- ☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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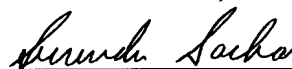
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Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 221608US0PCT		SERIAL NO. 10/089,067	
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Minoru TAKAYA, et al.			
				FILING DATE April 5, 2002		GROUP	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA	5128746	07/07/92	Motorola, Inc.			
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION		
					YES	NO	
	AO	8-174264	07/09/96	JP		No	
	AP	6-269980	09/27/94	JP		No	
	AQ	8-90283	04/09/96	JP		No	
	AR	7-80682	03/28/95	JP		No	
	AS	11-121915	04/30/99	JP (with English Abstract)		No	
	AT	59-5698	01/12/84	JP (with English Abstract)		No	
	AU	60-88495	05/18/85	JP (with English Abstract)		No	
	AV						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
	AW	"Latest mounting technology" ANBE MOUNTING TECHNOLOGY INSTITUTE LTD., EP/US BAG/CSP/FC, pages 18-27 '99 Overseas Technology Know-how Report 06/99					
	AX	Taro HUKUI: "Required characteristic and developing direction in under fill materials" HIGH-DENSITY MOUNTING TECHNOLOGY, vol. 5, pages 116-122 11/09/99					
	AY						
	AZ					<input type="checkbox"/> Additional References sheet(s) attached	
Examiner					Date Considered		
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							